25-06262

Standard Thick Film Chip Resistors

FEATURES

- Stability à*R*/*R* = 1 % for 1000 h at 70 ° C
- 2 mm pitch packaging option for 0603 size
- Pure tin solder contacts on Ni barrier layer provides compatibility with lead (Pb)-free and lead containing soldering processes
- Metal glaze on high quality ceramic
- AEC-Q200 qualified
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

STANDARD ELECTRICAL SPECIFICATIONS

MODEL	SIZE		RATED DISSIPATION P70 °C W	LIMITING ELEMENT VOLTAGE Umax. AC/DC	TEMPERATURE COEFFICIENT ppm/K	TOLERANCE %	RESISTANCE RANGE œ	SERIES
	INCH	METRIC						
D10/CRCW0402	0402	RR 1005M	0.063	50	± 100 ± 200	± 1 ± 5	1R0 to 10M	E24; E96 E24
			Zero-Ohm-Resistor: $R_{max.}$ = 20 mœ, $I_{max.}$ at 70 °C = 1.5 A					
D11/CRCW0603	0603	RR 1608M	0.10	75	± 100 ± 200	± 1 ± 5	1R0 to 10M	E24; E96 E24
			Zero-Ohm-Resistor: $R_{max.}$ = 20 mœ, $I_{max.}$ at 70 °C = 2.0 A					
D12/CRCW0805	0805	RR 2012M	0.125	150	± 100 ± 200	± 1 ± 5	1R0 to 10M	E24; E96 E24
			Zero-Ohm-Resistor: $R_{max.}$ = 20 mœ, $I_{max.}$ at 70 °C = 2.5 A					
D25/CRCW1206	1206	RR 3216M	0.25	200	± 100 ± 200	± 1 ± 5	1R0 to 10M	E24; E96 E24
			Zero-Ohm-Resistor: $R_{max.}$ = 20 mœ, $I_{max.}$ at 70 °C = 3.5 A					
CRCW1210	1210	RR 3225M	0.5	200	± 100 ± 200	± 1 ± 5	1R0 to 10M	E24; E96 E24
			Zero-Ohm-Resistor: $R_{max.}$ = 20 mœ, $I_{max.}$ at 70 °C = 5.0 A					
CRCW1218	1218	RR 3246M	1.0	200	± 100 ± 200	± 1 ± 5	1R0 to 2M2	E24; E96 E24
			Zero-Ohm-Resistor: $R_{max.}$ = 20 mœ, $I_{max.}$ at 70 °C = 7.0 A					
CRCW2010	2010	RR 5025M	0.75	400	± 100 ± 200	± 1 ± 5	1R0 to 10M	E24; E96 E24
			Zero-Ohm-Resistor: $R_{max.}$ = 20 mœ, $I_{max.}$ at 70 °C = 6.0 A					
CRCW2512	2512	RR 6332M	1.0	500	± 100 ± 200	± 1 ± 5	1R0 to 10M	E24; E96 E24
			Zero-Ohm-Resistor: $R_{max.}$ = 20 mœ, $I_{max.}$ at 70 °C = 7.0 A					

Notes

- These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime.
- Marking: See data sheet “Surface Mount Resistor Marking” (document number 20020).
- Power rating depends on the max. temperature at the solder point, the component placement density and the substrate material.

TECHNICAL SPECIFICATIONS

PARAMETER	UNIT	D10/ CRCW0402	D11/ CRCW0603	D12/ CRCW0805	D25/ CRCW1206	CRCW1210	CRCW1218	CRCW2010	CRCW2512
Rated dissipation P_{70} (1)	W	0.063	0.1	0.125	0.25	0.5	1.0	0.75	1.0
Limiting element voltage $U_{max.}$ AC/DC	V	50	75	150	200	200	200	400	500
Insulation voltage U_{ins} (1 min)	V	> 75	> 100	> 200	> 300	> 300	> 300	> 300	> 300
Insulation resistance	Ω	> 10^9							
Category temperature range	°C	- 55 to + 155							
Failure rate	h^{-1}	< 0.1 x 10^{-9}							
Weight	mg	0.65	2	5.5	10	16	29.5	25.5	40.5

Note

(1) The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature of 155 °C is not exceeded.

PART NUMBER AND PRODUCT DESCRIPTION

Part Number: CRCW0603562RFKEC

C	R	C	W	0	6	0	3	5	6	2	R	F	K	E	C		

MODEL	VALUE	TOLERANCE	TCR	PACKAGING	SPECIAL
CRCW0402 **CRCW0603** **CRCW0805** **CRCW1206** **CRCW1210** **CRCW1218** **CRCW2010** **CRCW2512**	**R** = Decimal **K** = Thousand **M** = Million **0000** = Jumper	**F** = ± 1.0 % **J** = ± 5.0 % **Z** = Jumper	**K** = ± 100 ppm/K **N** = ± 200 ppm/K **0** = Jumper	**EA, EB,** **EC, ED,** **EE, EF,** **EG, EH,** **EI, EL,** **EK**	Up to 2 digits

Product Description: D11/CRCW0603 100 562R 1 % ET6 e3

D11/CRCW0603	100	562R	1 %	ET6	e3
MODEL	TCR	RESISTANCE VALUE	TOLERANCE	PACKAGING	LEAD (Pb)-FREE
D10/CRCW0402 **D11/CRCW0603** **D12/CRCW0805** **D25/CRCW1206** **CRCW1210** **CRCW1218** **CRCW2010** **CRCW2512**	± **200** ppm/K ± **100** ppm/K	**10R** = 10 Ω **562R** = 562 Ω **10K** = 10 kΩ **1M0** = 1 MΩ **0R0** = Jumper	± **5 %** ± **1 %**	**ET1, ET2,** **ET3, ET4,** **ET5, ET6,** **ET7, ET8,** **ET9, EF4,** **E02, E67,** **E82**	**e3** = Pure tin termination finish

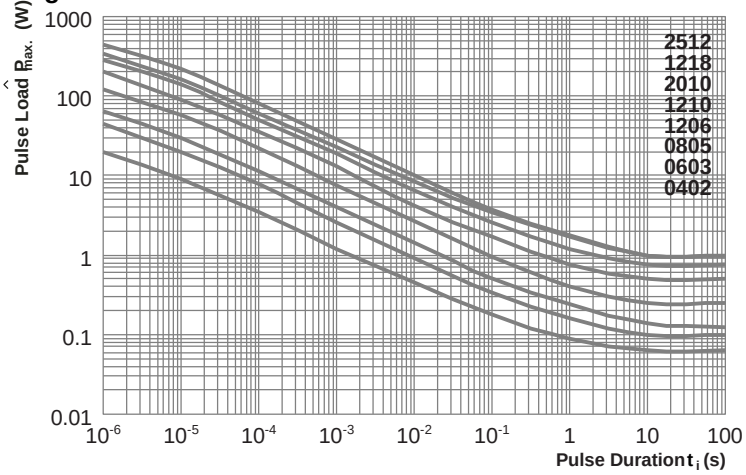
PACKAGING						
MODEL	**CODE**	**QUANTITY**	**CARRIER TAPE**	**WIDTH**	**PITCH**	**REEL DIAMETER**
CRCW0402	ED = ET7	10 000		8 mm	2 mm	180 mm/7"
	EE = EF4	50 000				330 mm/13"
CRCW0603	EI = ET2	5000	Paper tape acc. to IEC 60068-3 Type I	8 mm	2 mm	180 mm/7"
	ED = ET3	10 000				180 mm/7"
	EL = ET4	20 000				285 mm/11.25"
	EE = ET8	50 000				330 mm/13"
	EA = ET1	5000		8 mm	4 mm	180 mm/7"
	EB = ET5	10 000				285 mm/11.25"
	EC = ET6	20 000				330 mm/13"
CRCW0805	EA = ET1	5000		8 mm	4 mm	180 mm/7"
	EB = ET5	10 000				285 mm/11.25"
	EC = ET6	20 000				330 mm/13"
CRCW1206	EA = ET1	5000		8 mm	4 mm	180 mm/7"
	EB = ET5	10 000				285 mm/11.25"
	EC = ET6	20 000				330 mm/13"
CRCW1210	EA = ET1	5000		8 mm	4 mm	180 mm/7"
	EB = ET5	10 000				285 mm/11.25"
	EC = ET6	20 000				330 mm/13"
CRCW1218	EK = ET9	4000	Blister tape acc. to IEC 60068-3 Type II	12 mm	4 mm	180 mm/7"
CRCW2010	EF = E02	4000		12 mm	4 mm	180 mm/7"
CRCW2512	EG = E67	2000		12 mm	8 mm	180 mm/7"
	EH = E82	4000			4 mm	

DIMENSIONS

SIZE		DIMENSIONS in millimeters					SOLDER PAD DIMENSIONS in millimeters					
							REFLOW SOLDERING			WAVE SOLDERING		
INCH	**METRIC**	**L**	**W**	**H**	**T1**	**T2**	**a**	**b**	**l**	**a**	**b**	**l**
0402	1005	1.0 ± 0.05	0.5 ± 0.05	0.35 ± 0.05	0.25 ± 0.05	0.2 ± 0.1	0.4	0.6	0.5			
0603	1608	1.55 $^{+0.10}_{-0.05}$	0.85 ± 0.1	0.45 ± 0.05	0.3 ± 0.2	0.3 ± 0.2	0.5	0.9	1.0	0.9	0.9	1.0
0805	2012	2.0 $^{+0.20}_{-0.10}$	1.25 ± 0.15	0.45 ± 0.05	0.3 $^{+0.20}_{-0.10}$	0.3 ± 0.2	0.7	1.3	1.2	0.9	1.3	1.3
1206	3216	3.2 $^{+0.10}_{-0.20}$	1.6 ± 0.15	0.55 ± 0.05	0.45 ± 0.2	0.4 ± 0.2	0.9	1.7	2.0	1.1	1.7	2.3
1210	3225	3.2 ± 0.2	2.5 ± 0.2	0.55 ± 0.05	0.45 ± 0.2	0.4 ± 0.2	0.9	2.5	2.0	1.1	2.5	2.2
1218	3246	3.2 $^{+0.10}_{-0.20}$	4.6 ± 0.15	0.55 ± 0.05	0.45 ± 0.2	0.4 ± 0.2	1.05	4.9	1.9	1.25	4.8	1.9
2010	5025	5.0 ± 0.15	2.5 ± 0.15	0.6 ± 0.1	0.6 ± 0.2	0.6 ± 0.2	1.0	2.5	3.9	1.2	2.5	3.9
2512	6332	6.3 ± 0.2	3.15 ± 0.15	0.6 ± 0.1	0.6 ± 0.2	0.6 ± 0.2	1.0	3.2	5.2	1.2	3.2	5.2

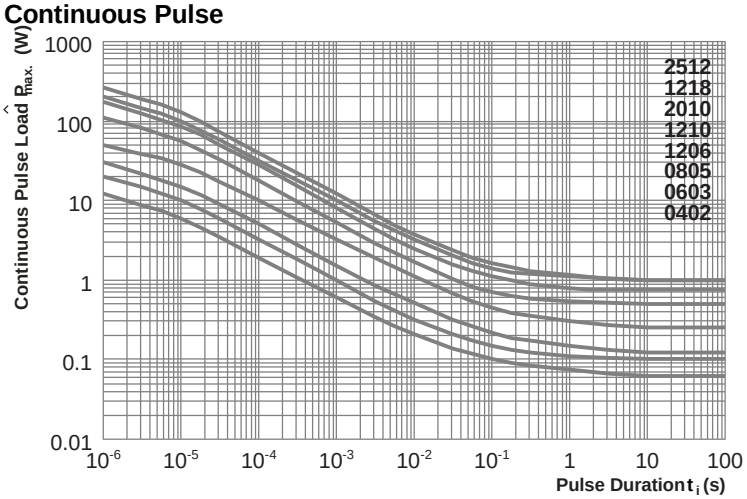
FUNCTIONAL PERFORMANCE

Single Pulse

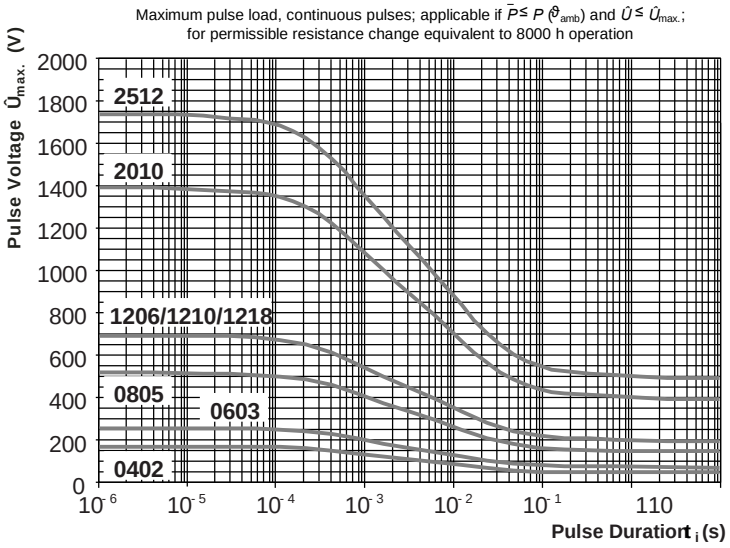


Maximum pulse load, single pulse; applicable if $\bar{P}$ 0 and n < 1000 and $\hat{U} \leq \hat{U}_{max.}$;
for permissible resistance change equivalent to 8000 h operation

Continuous Pulse

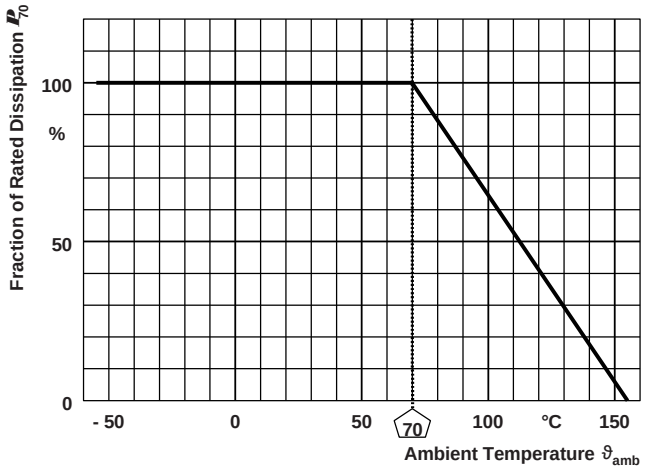


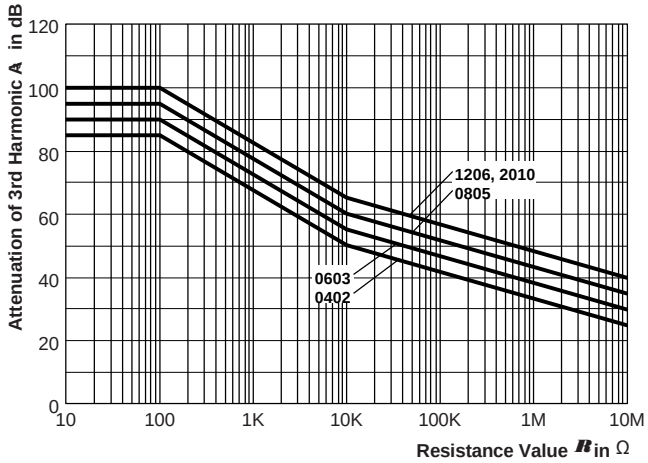
Maximum pulse load, continuous pulses; applicable if $\bar{P} \leq P(\vartheta_{amb})$ and $\hat{U} \leq \hat{U}_{max.}$;
for permissible resistance change equivalent to 8000 h operation

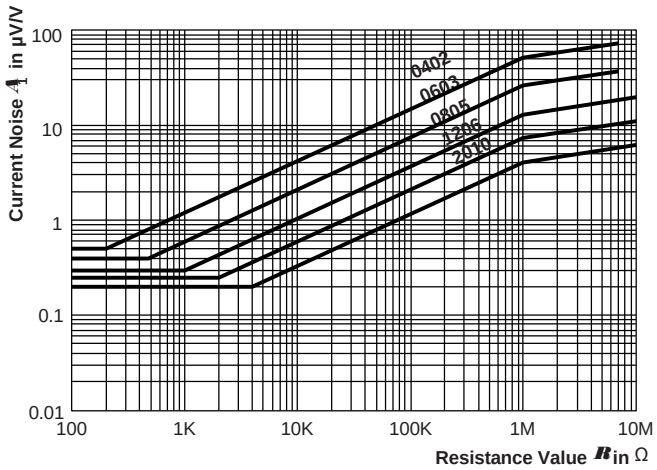


Maximum pulse voltage, single and continuous pulses; applicable if
$\hat{P} \leq \hat{P}_{max.}$; for permissible resistance change equivalent to 8000 h operation

Derating







TEST PROCEDURES AND REQUIREMENTS

EN 60115-1 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)	
				SIZE 0402 to 2512	
				STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER
			Stability for product types:		
			D/CRCW e3	1 Ω to 10M Ω	
4.5	-	Resistance	-	± 1 %	± 5 %
4.7	-	Voltage proof	U = 1.4 x U_{ins}; 60 s	No flashover or breakdown	
4.13	-	Short time overload	U= 2.5 x P_{70} x R or 2 x $U_{max.}$; duration: Acc. to style	± (0.25 % R + 0.05 Ω)	(0.5 % R + 0.05 Ω)
4.17.2	58 (Td)	Solderability	Solder bath method; Sn60Pb40 non activated flux; (235 ± 5) °C (2 ± 0.2) s	Good tinning (≥ 95 % covered) no visible damage	
			Solder bath method; Sn96.5Ag3Cu0.5 non-activated flux; (245 ± 5) °C (3 ± 0.3) s	Good tinning (≥ 95 % covered) no visible damage	
4.8.4.2	-	Temperature coefficient	(20/- 55/20) °C and (20/125/20) °C	± 100 ppm/K	± 200 ppm/K
4.32	21 (Uu_3)	Shear (adhesion)	RR 1608 and smaller: 9 N RR 2012 and larger: 45 N	No visible damage	
4.33	21 (Uu_1)	Substrate bending	Depth 2 mm; 3 times	No visible damage, no open circuit in bent position ± (0.25 % R + 0.05 Ω)	
4.19	14 (Na)	Rapid change of temperature	30 min. at - 55 °C; 30 min. at 125 °C 5 cycles 1000 cycles	± (0.25 % R + 0.05 Ω) ± (1 % R + 0.05 Ω)	± (0.5 % R + 0.05 Ω) (1 % R + 0.05 Ω)
4.23	-	Climatic sequence:	-	± (1 % R + 0.05 Ω)	(2 % R + 0.1 Ω)
4.23.2	2 (Ba)	Dry heat	125 °C; 16h		
4.23.3	30 (Db)	Damp heat, cyclic	55 °C; ≥ 90 %RH; 24 h; 1 cycle		
4.23.4	1 (Aa)	Cold	- 55 °C; 2h		
4.23.5	13 (M)	Low air pressure	1kPa; (25± 10) °C; 1h		
4.23.6	30 (Db)	Damp heat, cyclic	55 °C; ≥ 90 %RH; 24 h; 5 cycles		
4.23.7	-	DC load	U= P_{70} x R		
4.25.1	-	Endurance at 70 °C	U= P_{70} x R or $U_{max.}$; 1.5 h on; 0.5 h off;		
			70 °C; 1000 h	± (1 % R + 0.05 Ω)	(2 % R + 0.1 Ω)
			70 °C; 8000 h	± (2 % R + 0.1 Ω)	(4 % R + 0.1 Ω)

TEST PROCEDURES AND REQUIREMENTS					
EN 60115-1 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS PERMISSIBLE CHANGE (ΔR)	
				SIZE 0402 to 2512	
				STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER
			Stability for product types:		
			D/CRCW e3	1 Ω to 10M Ω	
4.18.2	58 (Td)	Resistance to soldering heat	Solder bath method (260 ± 5) °C; (10 ± 1) s	± (0.25 % R + 0.05 Ω)	± (0.5 % R + 0.05 Ω)
4.35	-	Flamability, needle flame test	IEC 60695-11-5; 10 s	No burning after 30 s	
4.24	78 (Cab)	Damp heat, steady state	(40 ± 2) °C; (93 ± 3) % RH; 56 days	± (1 % R + 0.05 Ω)	
4.25.3	-	Endurance at upper category temperature	155 °C, 1000 h	± (1 % R + 0.05 Ω)±	(2 % R + 0.1 Ω)
4.40	-	Electrostatic discharge (human body model)	IEC 61340-3-1; 3 pos. + 3 neg. discharges; ESD voltage acc. to size	± (1 % R + 0.05 Ω)	
4.29	45 (XA)	Component solvent resistance	Isopropyl alcohol; 50 °C; method 2	No visible damage	
4.30	45 (XA)	Solvent resistance of marking	Isopropyl alcohol; 50 °C; method 1, toothbrush	Marking legible, no visible damage	
4.22	6 (Fc)	Vibration, endurance by sweeping	f = 10 Hz to 2000 Hz; x, y, z ≙ 1.5 mm; A ≙ 200 m/s²; 10 sweeps per axis	± (0.25 % R + 0.05 Ω)	± (0.5 % R + 0.05 Ω)
4.37	-	Periodic electric overload	U= 15 x P_{70} x R ≙ 2 x $U_{max.}$; 0.1 s on; 2.5 s off; 1000 cycles	± (1 % R + 0.05 Ω)	
4.27	-	Single pulse high voltage overload, 10 µs/700 µs	$\hat{U}$= 10 x P_{70} x R ≙ 2 x $U_{max.}$; 10 pulses	± (1 % R + 0.05 Ω)	

All tests are carried out in accordance with the following specifications:

[35][17] EN 60115-1, generic specification

[35][17] EN 140400, sectional specification

[35][17] EN 140401-802, detail specification

[35][17] IEC 60068-2-x, environmental test procedures

Packaging of components is done in paper or blister tapes according to IEC 60286-3.

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